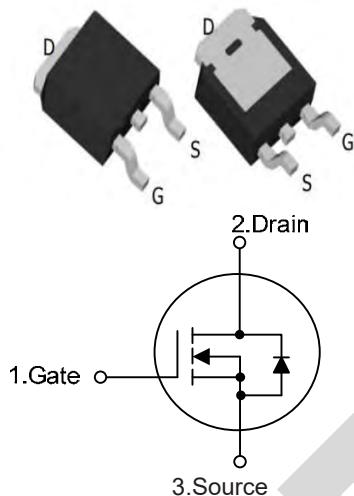


SGT N-channel Power MOSFET

MTR7R5N06D

TO-252



V_{DS}	60	V
$R_{DS(on),TYP}@ V_{GS}=10\text{ V}$	6.5	mΩ
I_D	55	A

Features

- 1、Low on – resistance
- 2、High power package (TO-252)
- 3、SGT N-channel Power MOSFET

Applications

- 1、Load Switch for Portable Devices
- 2、DC/DC Converter

Maximum ratings, at $T_A=25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V(BR)DSS$	Drain-Source breakdown voltage	60	V
V_{GS}	Gate-Source voltage	± 20	V
I_S	Diode continuous forward current	$T_c=25^\circ\text{C}$	A
I_D	Continuous drain current @ $V_{GS}=10\text{V}$	$T_c=25^\circ\text{C}$	A
		$T_c=100^\circ\text{C}$	A
I_{DM}	Pulse drain current tested ①	$T_c=25^\circ\text{C}$	A
I_{DSM}	Continuous drain current @ $V_{GS}=10\text{V}$	$T_A=25^\circ\text{C}$	A
		$T_A=70^\circ\text{C}$	A
E_{AS}	Avalanche energy, single pulsed ②	20	mJ
P_D	Maximum power dissipation	$T_c=25^\circ\text{C}$	W
		$T_c=100^\circ\text{C}$	W
P_{DSM}	Maximum power dissipation ③	$T_A=25^\circ\text{C}$	W
		$T_A=70^\circ\text{C}$	W
$T_{STG,TJ}$	Storage and Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	3.4	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	30	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @ T_j=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current (T _j =125°C)	V _{DS} =60V, V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.3	1.9	2.5	V
R _{D(on)}	Drain-Source On-State Resistance ④	V _{GS} =10V, I _D =20A	--	6.5	7.5	mΩ
		V _{GS} =4.5V, I _D =20A	--	10	12	mΩ

Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1MHz	995	1170	1345	pF
C _{oss}	Output Capacitance		500	585	670	pF
C _{rss}	Reverse Transfer Capacitance		--	20	30	pF
R _g	Gate Resistance	f=1MHz	--	1.3	--	Ω
Q _g (10V)	Total Gate Charge	V _{DS} =30V, I _D =30A, V _{GS} =10V	--	22	--	nC
Q _g (4.5V)	Total Gate Charge		--	12	--	nC
Q _{gs}	Gate-Source Charge		--	4.2	--	nC
Q _{gd}	Gate-Drain Charge		--	5.5	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	$V_{DD}=30V$, $I_D=30A$, $R_G=3\Omega$, $V_{GS}=10V$	--	7.4	--	ns
Tr	Turn-on Rise Time		--	43	--	ns
Td(off)	Turn-Off Delay Time		--	18	--	ns
Tf	Turn-Off Fall Time		--	6.2	--	ns

Source- Drain Diode Characteristics@ $T_j = 25^\circ C$ (unless otherwise stated)

VSD	Forward on voltage	$I_{SD}=20A, V_{GS}=0V$	--	0.9	1.3	V
Trr	Reverse Recovery Time	$T_j=25^\circ C, I_{SD}=20A$, $V_{GS}=0V$ $di/dt=100A/\mu s$	--	26	--	ns
Qrr	Reverse Recovery Charge		--	15	--	nC

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

- ② Limited by T_{Jmax} , starting $T_J = 25^\circ C$, $L = 0.5mH$, $R_G = 25\Omega$, $I_{AS} = 9A$, $V_{GS} = 10V$. Part not recommended for use above this value
- ③ The power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of $150^\circ C$.
- ④ Pulse width $\leq 380\mu s$; duty cycle $\leq 2\%$.

Typical Characteristics

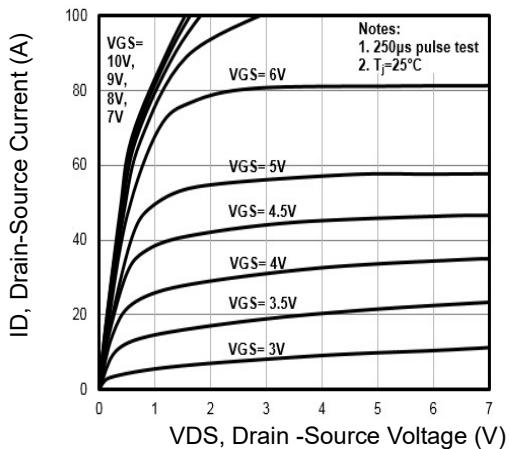


Fig1. Typical Output Characteristics

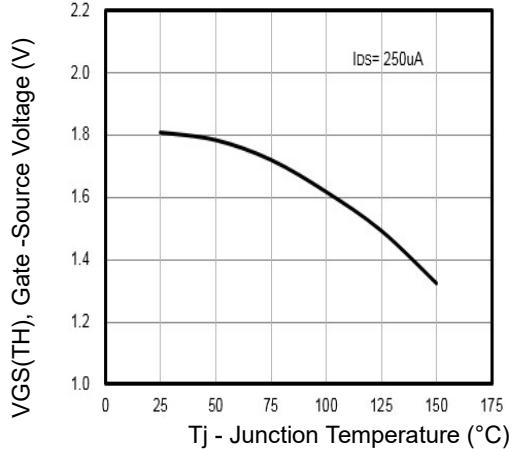


Fig2. $V_{GS(TH)}$ Gate -Source Voltage Vs. T_j

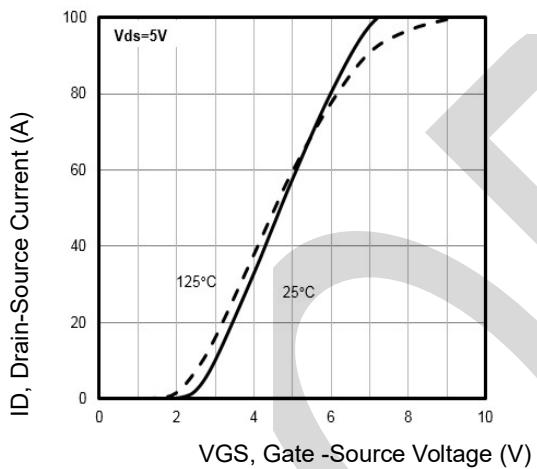


Fig3. Typical Transfer Characteristics

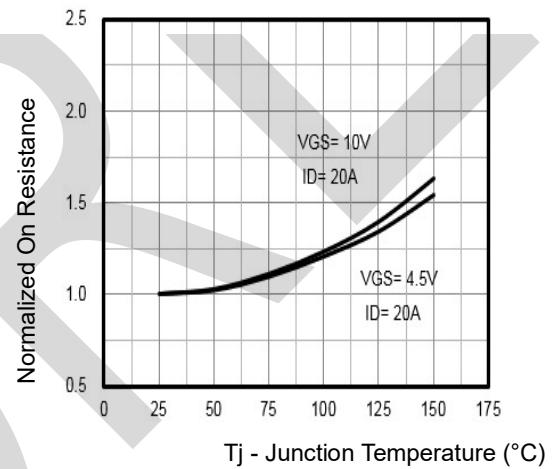


Fig4. Normalized On-Resistance Vs. T_j

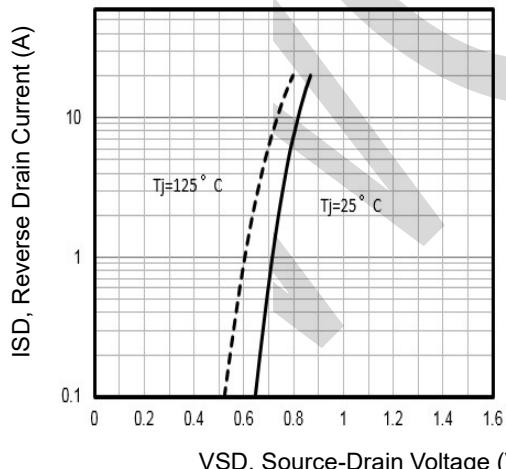


Fig5. Typical Source-Drain Diode Forward Voltage

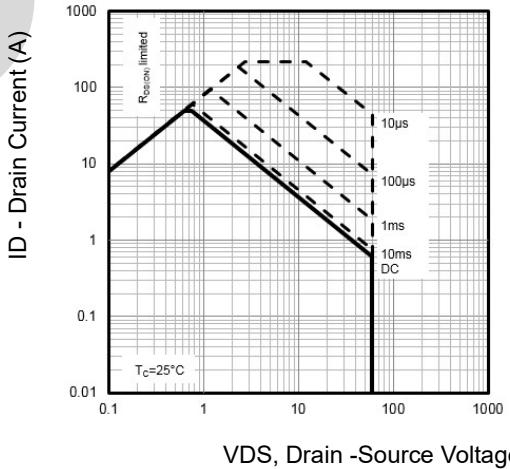


Fig6. Maximum Safe Operating Area

Typical Characteristics

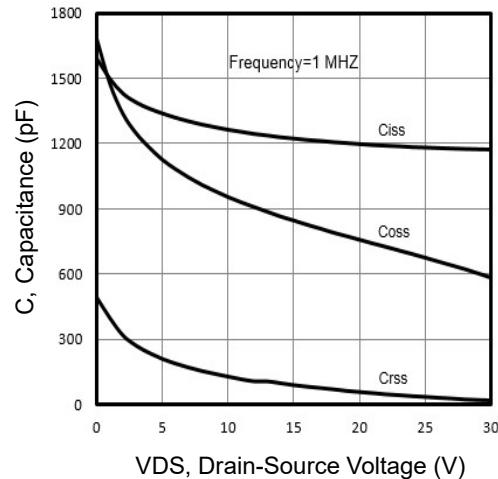


Fig7. Typical Capacitance Vs. Drain-Source Voltage

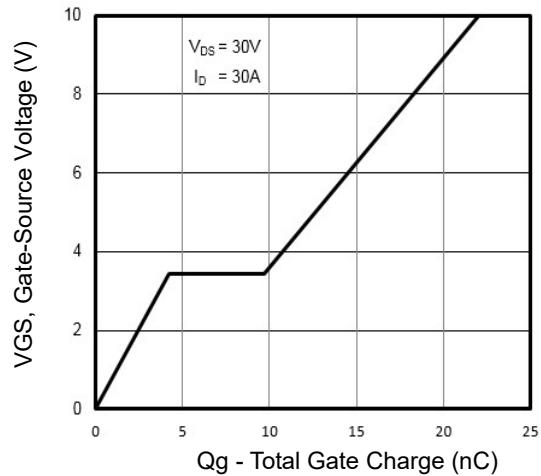


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

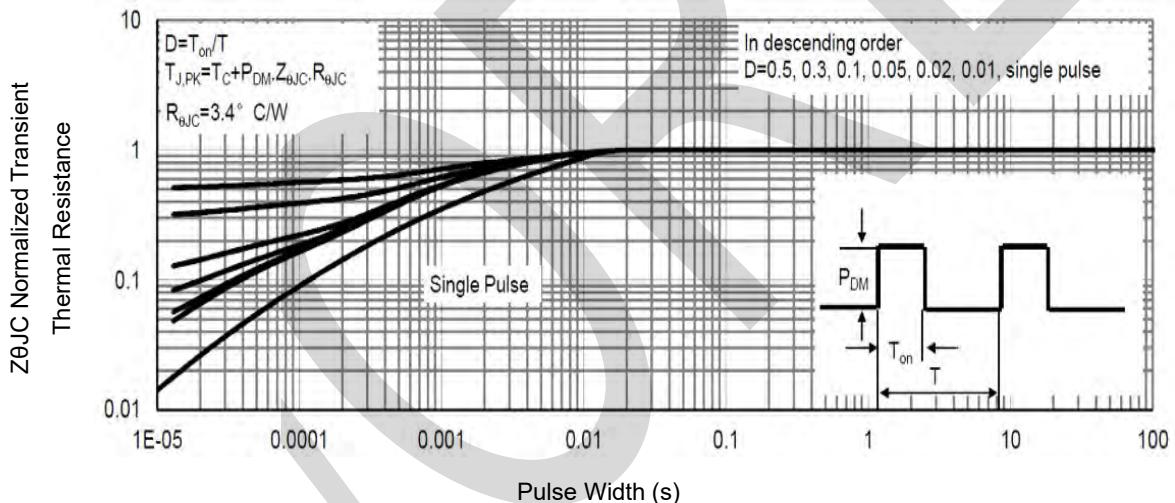


Fig9. Normalized Maximum Transient Thermal Impedance

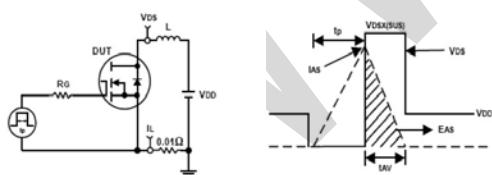


Fig10. Unclamped Inductive Test Circuit and waveforms

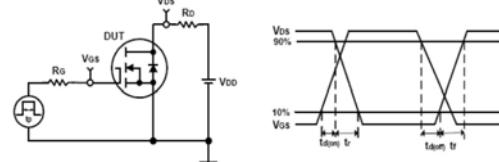
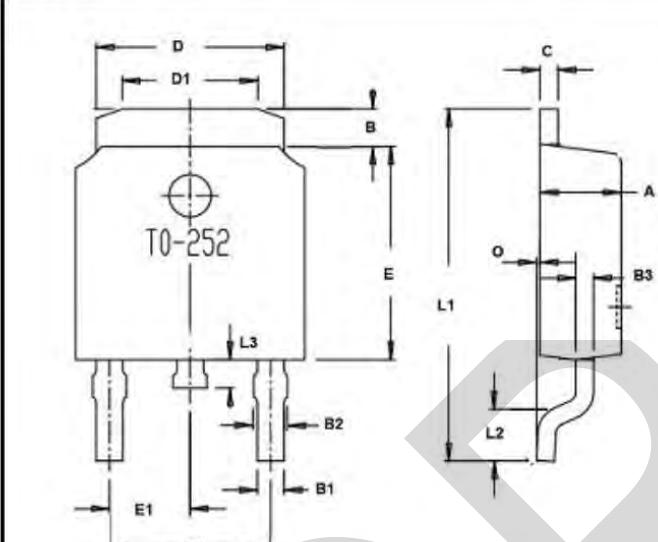


Fig11. Switching Time Test Circuit and waveforms

PACKAGE OUTLINE DIMENSIONS

Note: unit mm

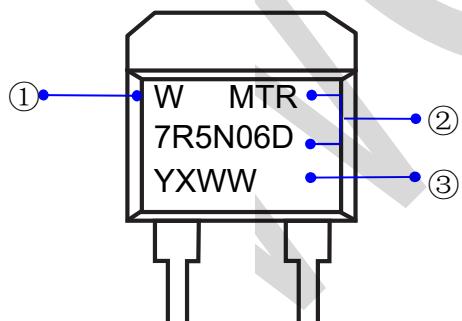
TO-252



Dim.	Min.	Max.
A	2.15	2.45
B	0.96	1.42
C	Typ0.5	
D	5.33	5.53
D1	3.65	4.05
E	6.0	6.2
E1	Typ2.29	
E2	Typ4.58	
B1	0.74	0.86
B2	0.74	0.94
O	0	0.15
L1	9.9	10.5
L2	Typ1.65	
L3	0.6	1.0

All Dimensions in millimeter

Marking Information



①W : Company's trademark

②Product model : MTR7R5N06D

③PDC information:

